



Qualitek Group Of Companies

DSP 888D
LEAD FREE
NO CLEAN
DISPENSING SOLDER
PASTE

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Physical Properties

Solder Composition

Qualitek Bi58 is designed as a lead-free alternative for Sn/Pb alloys for electronics assembly operations. The Qualitek Bi58 alloy conforms and exceeds the impurity requirements of J-Std-006 and all other relevant international standards.

Typical Analysis													
Sn	Ag	Cu	Pb	Sb	Bi	In	As	Fe	Ni	Cd	Al	Zn	Au
Bal	0.020 Max	0.050 Max	0.050 Max	0.050 Max	57.5- 58.5	0.050 Max	0.010 Max	0.010 Max	0.005 Max	0.001 Max	0.001 Max	0.001 Max	0.002 Max

	Sn42/Bi58	Sn63/Pb37		Sn42/Bi58	Sn63/Pb37
Melting Point, ° C	138E	183 E	Yield Strength, psi	7119	3950
Hardness, Brinell	22HB	14HB	Total Elongation,%	46	48
Coefficient of Thermal Expansion	13.8	24.7	Shear Strength MPa, at 1mm/min 20 C	27	34.5
Tensile Strength, psi	5400	4442	Shear Strength MPa, at 1mm/min 100 C	15.6	21.6
Density, g/cc	8.72	8.42	Fatigue Strength, Mpa at 1000 cycles 20 C	16	16.2
Electrical Resistivity , (μohm-cm)	34.5	14.5	Fatigue Strength, Mpa at 1000 cycles 100 C	7.9	10.2
Electrical Conductivity, %IACS	4.5	11.9	Specific Heat (J/g)	46	45

Particle Size

Sn/Ag/Cu alloys are available in Type 2 (75-45μm), 3(45-25μm), 4(38-20μm), and 5 (25-15μm) J-STD-005 powder distribution. Solder powder distribution is measured utilizing laser diffraction, optical analysis and sieve analysis. Careful control of solder powder manufacturing processes ensures the particles' shape are 95% spherical minimum (aspect ratio < 1.5) and that the alloy contains a typical maximum oxide level of 80 ppm.

Powder Type	Fines	Majority			Coarse		Typical Mesh
		<10%	>80%	>90%	<1%	0%	
1	20	20	75-150		150	160	100/200
2	20		45-75		75	80	200/325
3	20		25-45		45	50	325/500
4	20			20-38	38	40	400/635
5	15			15-25	25	30	500

Metal Loading

Typical metal loading for dispensing application is **85-87%**. Compared to typical Sn63/Sn62 solder pastes manufactured with 88% by weight metal loading, DSP 888D Lead Free provides as much as 10-12% higher metal volume than Sn63/Sn62. This increased in volume of DSP 888D promotes better wetting and spreading of Sn42/Bi58 Lead Free alloy.

Solder Paste

Qualitek has developed a unique flux system designed specifically for high temperature lead free alloys. It provides the fluxing activity levels that promote thermal stability and prevents thermal degradation when reflowing under air atmosphere (normal). Since use of nitrogen is not required, DSP 888D Lead Free Solder paste will provide excellent cost savings.

In addition, DSP 888D Lead Free solder paste exhibits superior joint strength, excellent wettability, extraordinary print definition and tack life. The post soldering residues of DSP 888D are non-conductive, non-corrosive and highly insulated.

Main Features

- Low residues
- Easily dispensed
- Long tack time
- Excellent wettability
- Hard non-conductive residues

	Specification	Test Method
Flux Classification	ROLO	JSTD-004
Copper Mirror	No removal of copper film	IPC-TM-650 2.3.32
Silver Chromate	Pass	IPC-TM-650 2.3.33
Corrosion	Pass	IPC-TM-650 2.6.15
SIR		
JSTD-004	6.41 x 10 ¹¹ ohms	IPC-TM-650 2.6.3.3
Bellcore (Telecordia)	5.12 x 10 ¹¹ ohms	Bellcore GR-78-CORE 13.1.3
Electromigration	Pass	Bellcore GR-78-CORE 13.1.4
Post Reflow Flux Residue	45%	TGA Analysis
Acid Value	110	IPC-TM-650 2.3.13
Metal Loading	87%	IPC-TM-650 2.2.20
Viscosity		
Brookfield ⁽¹⁾ , kcps	400+/-10% kcps	IPC-TM-650 2.4.34 modified
Malcom ⁽²⁾ , poise	850-1100	IPC-TM-650 2.4.34.3 modified
Thixotropic Index	0.50-0.60	
Slump Test		
25 C, 0.63 vertical/horizontal	No bridges all spacings	IPC-TM-650 2.4.35
150 C, 0.63 vertical/horizontal	No bridges all spacings	IPC-TM-650 2.4.35
25 C, 0.33 vertical/horizontal	0.15 /0.15	IPC-TM-650 2.4.35
150 C, 0.33 vertical/horizontal	0.20/0.20	IPC-TM-650 2.4.35
Solder Ball Test	Pass	IPC-TM-650 2.4.43
Tack		
Initial	114 gm	JIS Z 3284
Tack retention @ 24 hr	105 gm	JIS Z 3284
Tack retention @ 72 hr	96 gm	JIS Z 3284

Printing**Dispensing**

Needle Gauge	Needle inner diameter		Applicable powder (mesh cut)
	in.	μm	
18	0.033	838	-200+325
20	0.023	584	-325+500
21	0.020	508	-325+500
22	0.016	406	-325+500
23	0.013	330	-325+500
25	0.010	254	-400+635
27	0.008	203	-500

The clearance gap between the needle and the substrate affects the shape and quality of the dot dispensed. If the clearance is too little, the dot tends to be flattened out, and if too large, the dot tends to have long tailing.

Pressure

The pressure applied in the syringe should be kept at a minimum, and the proper head pressure kept in the range of 15-25 lb/in² (1.05-1.76 kg/cm²). In cases where a paste requires much higher pressure (more than 40 lb/in² or 2.82 kg/cm²) to dispense, the paste will become inconsistent and clogging may be expected. The external air pressure supply should be maintained constant.

Open & Abandon Time

Tests have proven that DSP 888D will perform during continuous dispensing for up to 8 hrs. The paste can be left in the dispensing unit for up to 4 hours without paste drying out. If extended downtime is expected (>4 hrs), the whole dispensing system should be flushed without leaving any paste in any part of the system.

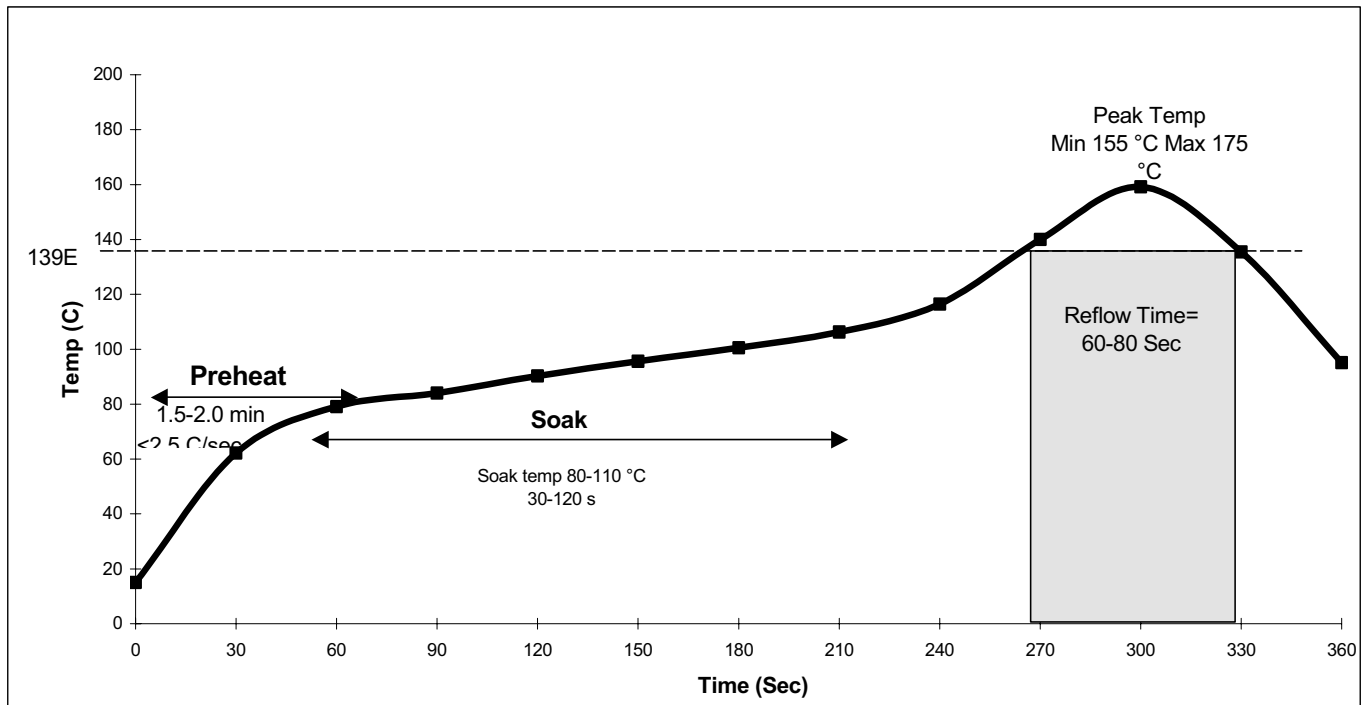
Paste Application

Solder paste should be taken out of the refrigerator at least 3 to 6 hours prior to use. This will give the paste enough time to come to thermal equilibrium with the environment. The flow rate of paste in a dispensing application depends on viscosity, which can be altered by temperature change. If solder paste is supplied in syringes pre-mixing is not necessary due to the shear action produced from the dispensing.

Reflow

Best results have been achieved when DSP 888D is reflowed in a **forced air convection** oven with a minimum of 8 zones (top&bottom), however reflow is possible with a 4 zone oven (top & bottom).

The following is a recommended profile for a forced air convection reflow process. The melting temperature of the solder, the heat resistance of the components, and the characteristics of the PCB (i.e. density, thickness, etc.) determine the actual reflow profile.



Storage & Shelf Life

It is recommended that solder paste be stored at a temperature of between 35-50 °F (2-10 °C) to minimize solvent evaporation, flux separation, and chemical activity. If room temperature storage is necessary it should be maintain between 68-77°F (20-25 °C) .

Shelf life

Unopened Container (35-50°F/2-10°C) 6 months (from DOM)

Unopened Container (68-77°F/20-25 °C) 3 months (from DOM)

Opened Container (68-77°F/20-25 °C) 24 hours

Reusing Solder Paste

This is not normally recommended, because it typically generates more problems than it is worth. If you do decide to reuse solder paste, these pointers may be helpful. This paste should be tightly sealed and refrigerated. Then, the paste may be reused at a later date, provided that the paste has not separated or thickened significantly compared to its original properties. Storage of syringes is preferred in an upright position with tip down to prevent flux separation and air entrapment.

Working Environment

Solder paste performs best when used in a controlled environment. Maintaining ambient temperature of between 68-77 °F (20-25 °C) at a relative humidity of 40-65% will ensure consistent performance and maximum life of paste.

Cleaning Misprint Boards

If you should have a misprinted board, the paste may be cleaned off manually with alcohol (IPA) or Qualitek stencil cleaner, SK-11. If you have a more elaborate board cleaner, the paste may be easily removed with use of a 5% saponifier solution in hot DI water. Qualitek SK-44 saponifier could be used in this process.

Stencil Cleaning

Periodic cleaning of the stencil during production is recommended to prevent any paste from being deposited in unwanted areas of the board. Without stencil cleaning, solder balling will increase. We recommend a periodic dry wipe (every 5 to 10 boards) with an occasional wet wipe (every 15 to 25 boards). When running fine pitch boards, the cleaning may need to become more frequent. The wet wipes should be performed with either alcohol or a stencil cleaner. Qualitek SK-11 stencil cleaner is designed for this purpose. When cleaning the stencil at the end of a job, the cleaning should be more thorough. If you have stencil cleaning equipment Qualitek SK- 44 Stencil Cleaner Saponifier is highly recommended for stencil cleaning purposes.

Disposal

DSP 888D should be stored in a sealed container and disposed of in accordance with state & local authority requirements.

Packaging

10cc	35 gm
30cc	100 gm